

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3386212

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHANG-MING WU	05/29/2015
	SHIH-CHANG LIU	05/29/2015
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	
Street Address:	NO. 8, LI-HSIN RD. 6	
Internal Address:	HSIN-CHU SCIENCE PARK	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	300-77	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14713462	
CORRESPONDENCE DATA		
Fax Number:	(216)502-0601	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	216-502-0600	
Email:	docketing@eschweilerlaw.com	
Correspondent Name:	ESCHWEILER & ASSOCIATES, LLC.	
Address Line 1:	629 EUCLID AVENUE, SUITE 1000	
Address Line 2:	NATIONAL CITY BANK BUILDING	
Address Line 4:	CLEVELAND, OHIO 44114	
ATTORNEY DOCKET NUMBER:	TSMCP562US	
NAME OF SUBMITTER:	JAME	
SIGNATURE:	/James R. Potashnik/	
DATE SIGNED:	06/08/2015	
Total Attachments: 4		
source=Assignment#page1.tif		
source=Assignment#page2.tif		
source=Assignment#page3.tif		

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

Chang-Ming Wu
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

Assignor(s):

Shih-Chang Liu
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
Hsin-Chu, Taiwan 300-77
Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled

“A MEMORY CELL STRUCTURE FOR IMPROVING ERASE SPEED” for which:

a non-provisional application for United States Letters Patent:

☒ was executed on even date preparatory to filing (each inventor should sign this

Assignment on the same day as he/she signs the Declaration); or

☐ was filed on _____ and accorded U.S. Serial No. _____; or

☐ I hereby authorize and request my attorney associated with Customer No.

107476, to insert on the designated lines below the filing date and application

number of said application when known:

U.S. Serial No. _____,

filed on _____.

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

TSMC Docket No. P20150139US00
Docket No. TSMCP562US

2015/5/29
Date

Chang-Ming Wu
Name 1st Inventor Chang-Ming Wu

TSMC Docket No. P20150139US00
Docket No. TSMCP562US

2015-05-29
Date

Shih-Chang Liu
Name 2nd Inventor Shih-Chang Liu